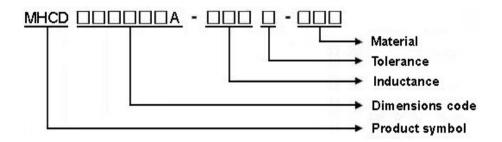


Halogen Free & RoHs Compliance

SPECIFICATION FOR APPROVAL

CUSTOMER:				
CUSTOMER P/N:				
OUR DWG No:				
QUANTITY:	0	Pcs.	DATE:	2014/06/09
ITEM:		MHC	D252010A-	R47M-A8L
		ECIFIC/ CEPTE	_	
COMPONENT	AC	OLFIL	<u> </u>	
ENGINEER				
ELECTRICAL				
ENGINEER				
MECHANICAL				
ENGINEER				
APPROVED				
REJECTED				
奇力新電子股份有限公司 Chilisin Electronic sCorp No. 29, Alley 301, Tehhsin Rd. Hukou,Hsinchu 303, Taiwan TEL: +886-3- 599-2646 FAX: +886-3- 599-9176 E-mail: sales@chilisin.com.tw http://www.chilisin.com.tw	,	Chili No. Area Gua TEL FAX	R奇力新電子 sin Electronics (I 78, Puxing Rd., \ a, Qingxi Town, D ngdong,China :+86-769-8773 :+86-769-8773 ail:cect@chilisi	Dongguan) Co., Ltd. /uliangwei Administration longguan City, 0251~3 I-0232
奇力新電子(河南)有限公 Chilisin Electronics (Henan) Co XiuWu Xian, industry gathering JiaoZuo, Henan China Postal Code:454350 TEL:+86-391-717-0682 FAX:+86-391-717-0666	o., Ltd.	Chili No.1 Suzł Post TEL	,	Suzhou) Co., Ltd. ld., Suzhou New District, 350 356
DRAWN BY 張鈺雯 chang.yuwen		CHECKED 溫美玲 1) BY	APPROVED BY 張鈺雯 chang.yuwen

- 1 Scope: This specification applies to Alloy Molding power inductors
- 2 Part Numbering: Product Identification



3 Rating:

Operating Temperature: $-4~0~\mathrm{C}\!\sim\!1~2~5~\mathrm{C}$ (Including self - temperature rise)

Storage Temperature: $-4~0~\%\sim1~2~5~\%$ (after PCB)

-5 $^{\circ}$ $^{\circ}$ $^{\circ}$ 3 5 $^{\circ}$ 7, Humidity 4 5 $^{\circ}$ $^{\circ}$ 8 5 $^{\circ}$ 6 (before PCB)

4 Marking:

No Marking

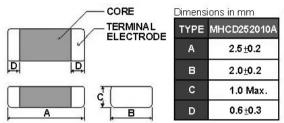
5 Standard Testing Condition

	Unless otherwise specified	In case of doubt	
Temperature	Ordinary Temperature(15 to 35℃)	20±2 ℃	
Humidity	Ordinary Humidity(25 to 85% RH)	60 to 70 % RH	



MHCD252010A Series Specification

6 Configuration and Dimensions:



7 ELECTRICAL CHARACTERISTICS :

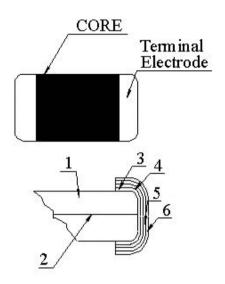
Part No.	Inductance (uH)	Test Freq.	Irms(A) Max.(Typ)	Isat(A) Max.(Typ)	RDC(mΩ) Max.(Typ)	Tolerance (±%)	
MHCD252010A-R47M-A8L	0.47	2MHz,0.2V	3.4(3.9)	4.2(4.7)	35(29)	20	

NOTE:

- 1.Operating temperature range $-4~0~\text{C}\sim 1~2~5~\text{C}$ (Including self temperature rise)
- 2.Irms DC current (A) that will cause an approximate ΔT of 40°C.
- 3.Isat DC current (A) that will cause Lo to drop approximately 30%
- 4.All test data is referenced to 25℃ ambient

8 MHCD252010A Series

8.1 Construction:



8.2 Material List:

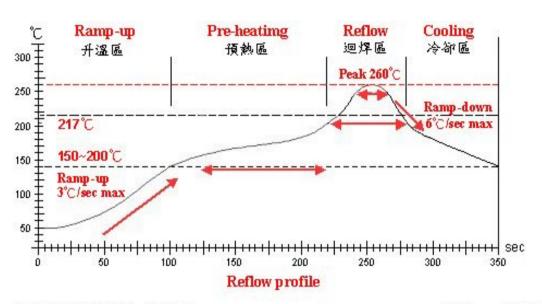
NO	Part	Description
1	Core	Metal Power
2	Wire	Copper wire
3	Sputter/Plating	Cu
4	Silver Electrode	Ag
5	Plating	Ni
6	Plating	Sn



MHCD252010A Series Specification

	ltem	Specification	Test Method		
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm		
-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs		
-1-3	Resistance to Soldering Heat				
-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150°C, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245±5°C Immersion Time: 4±1sec		
	Terminal Strength Test	No split termination Chip Mounting Pad	Test device shall be soldered on the substrate, then apply a force in the direction of the arrow. Force: 5N Keeping Time: 10±1sec		
	nvironmental Performance		Took Nackle Ava		
No I-2-1	Item Temperature Cycle	Specification Appearance: No damage Inductance:within±20% of initial value	Test Method One cycle:		
1-2-2	Humidity Resistance		Temperature: 60±2°C Relative Humidity: 90 ~ 95% / Time: 500hrs Measured after exposure in the room condition for 12h		
-2-3	High Temperature Resistance		Temperature: 85±3°C Relative Humidity: 0% / Time: 500hrs Measured after exposure in the room condition for 12hi		
-2-4	Low Temperature Resistance		Temperature: -40±3°C Relative Humidity: 0% / Time: 500hrs Measured after exposure in the room condition for 12h		





Lead-Free(LF) 標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heatimg	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T. ~150°ℂ	150°C ~ 200°C	217℃	260±5°⊂	Peak Temp. ~ 150°C
標準時間 Time spec.	_	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	1 - 1
實際時間 Time result	_	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	1 - 1

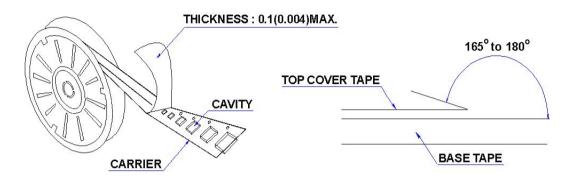
NOTE:

- 1. Re-flow possible times: within 2 times
- 2. Nitrogen adopted is recommended while in re-flow

11 PACKAGING

11.1 Packaging -Cover tape

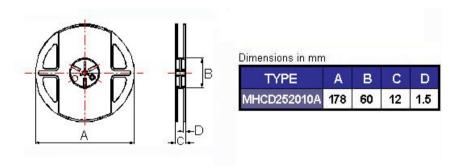
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



11.2 Packaging Quantity

TYPE	BULK	PCS/REEL
MHCD252010A	V	3000

11.3 Reel Dimensions

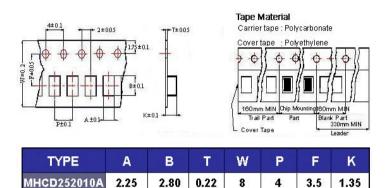




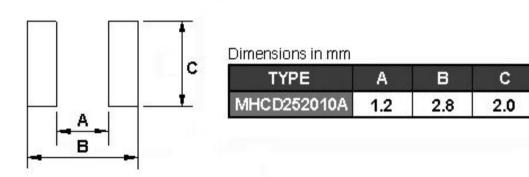
MHCD252010A Series Specification

11 PACKAGING

11.4 Tape Dimensions in mm



12 Recommended Pattern



13 Note:

- 1. Please make sure that your product is has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)

单击下面可查看定价,库存,交付和生命周期等信息

>>CHILISIN(奇力新)